

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TOSHIHIKO TAKEDA	01/24/2014
HIROYUKI NISHIMURA	01/24/2014
KATSUNARI OBATA	01/27/2014
RECEIVING PARTY DATA	
Name:	DAI NIPPON PRINTING CO., LTD.
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Internal Address:	SHINJUKU-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	162-8001
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14370875
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NAME OF SUBMITTER:	ERIC JENSEN
SIGNATURE:	/Eric Jensen/
DATE SIGNED:	07/07/2014
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 1 source=ASSMT#page1.tif	

ASSIGNMENT AND INVENTOR'S DECLARATION

WHEREAS I/we, the undersigned inventor(s), hereafter also referred to as "assignor(s)", have invented certain new and useful improvements described in the application identified below; and

WHEREAS, DAI NIPPON PRINTING CO., LTD., hereinafter referred to as "assignee(s)", whose address is 1-1, Ichigaya-kaqacho 1-chome, Shinjuku-ku, Tokyo 162-8001 Japan, is desirous of acquiring the entire right, title and interest in and to the application and invention, and to any United States patents to be obtained therefor;

NOW, THEREFORE, for valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I/we, the above-named assignor(s), hereby sell, assign and transfer to the above named assignee(s), its successors and assigns, the entire right, title and interest in the application and the invention disclosed therein for the United States of America, including all divisions, and continuations thereof, and all Letters Patent of the United States that may be granted thereon, and all reissues thereof, including any right to bring or maintain an action for infringement under the provisional rights granted pursuant to Title 35, Section 154 of the United States Code or any other cause of action for acts which would constitute infringement occurring prior to this assignment, and including the right to claim priority under the International Convention of Paris (1883), as amended, of or in any corresponding foreign patent application, and I/we request the Director of the U.S. Patent and Trademark Office to issue any Letters Patent granted upon the invention set forth in the application to the assignee(s), its successors and assigns.

As a below named inventor, I hereby declare that:

This assignment and declaration The attached application, or is directed to:
 United States Application or PCT International Application Number 14/370,875
 filed on July 7, 2014 (Confirmation No. 9434).

The application is entitled METHOD FOR PRODUCING VAPOR DEPOSITION MASK, AND METHOD FOR PRODUCING ORGANIC SEMICONDUCTOR ELEMENT
 The above-identified application was made or was authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this assignment with declaration is punishable under 18 USC 1001 by fine or imprisonment of not more than five (5) years, or both.

Given Name(s)	Toshihiko	Family Name/Surname(s)	TAKEDA
Inventor's Signature:	<i>Toshihiko Takeda</i>	Date	<i>Jan 24, 2014</i>
Given Name(s)	Hiroyuki	Family Name/Surname(s)	NISHIMURA
Inventor's Signature:	<i>Hiroyuki Nishimura</i>	Date	<i>Jan. 24, 2014</i>
Given Name(s)	Katsunari	Family Name/Surname(s)	OBATA
Inventor's Signature:	<i>Katsunaru Obata</i>	Date	<i>Jan. 27, 2014</i>
Given Name(s)		Family Name/Surname(s)	
Inventor's Signature:		Date	PATENT